

#### **Features**

- Low R<sub>DS(on)</sub> & FOM
- · Extremely Low Switching Loss
- · Excellent Stability and Uniformity
- · Fast Seitching and Soft Recovery
- Epoxy Meets UL 94 V-0 Flammability Rating
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

## **Maximum Ratings**

Operating Junction Temperature Range : -55°C to +150°C

• Storage Temperature Range: -55°C to +150°C

• Thermal Resistance: 104°C/W Junction to Ambient (t≤10S) (Note 2)

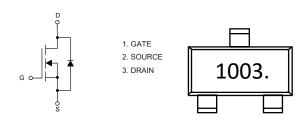
Thermal Resistance: 140°C/W Junction to Ambient(Steady-State)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V <sub>DS</sub>	100	V
Gate-Source Volltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>A</sub> =25°C	I <sub>D</sub>	3	Α
	T <sub>A</sub> =70°C		2.4	Α
Pulsed Drain Current (Note 3)		I <sub>DM</sub>	12	Α
Total Power Dissipation		P <sub>D</sub>	1.2	W

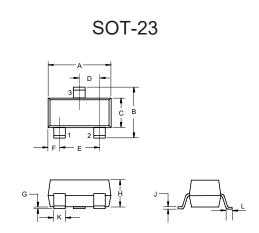
Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

- 2. Device Mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.
- 3. Pulse Test: Pulse Width≤300µs,Duty Cycle ≤2%.

## **Internal Structure and Marking Code**

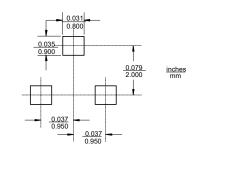


# N-CHANNEL MOSFET



	DIMENSIONS				
DIM INCHE		HES MM		NOTE	
DIIVI	MIN	MAX	MIN	MAX	NOIL
Α	0.110	0.120	2.80	3.04	
В	0.083	0.104	2.10	2.64	
С	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
Е	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
Н	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

#### Suggested Solder Pad Layout



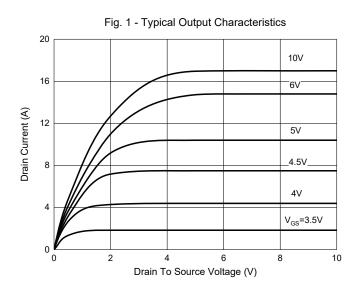


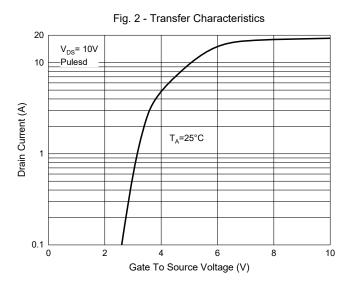
## Electrical Characteristics @ 25°C (Unless Otherwise Specified)

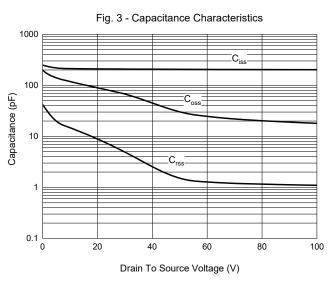
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics				1			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100			V	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μΑ	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1	1.8	2.5	V	
D : 0 D : 1	Б	V <sub>GS</sub> =10V, I <sub>D</sub> =3A		110	140	mΩ	
Drain-Source On-Resistance	$R_{DS(on)}$	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A		160	300	mΩ	
Diode Characteristics	'		'				
Continuous Body Diode Current	Is				3	Α	
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =3A		0.8	1.2	V	
Reverse Recovery Time	t <sub>rr</sub>			32		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>S</sub> =3A,di/dt=100A/μs		39		nC	
Peak Reverse Recovery Current	I <sub>rrm</sub>			2.1		Α	
Dynamic Characteristics							
Input Capacitance	C <sub>iss</sub>			206			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,f=1MHz		29		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			1.4		1	
Total Gate Charge	Q <sub>g</sub>			4.3			
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =50V,V <sub>GS</sub> =10V,I <sub>D</sub> =3A		1.5		nC	
Gate-Drain Charge	$Q_{gd}$			1.1			
Turn-On Delay Time	t <sub>d(on)</sub>			14.7			
Turn-On Rise Time	t <sub>r</sub>	$V_{GS}$ =10V, $V_{DD}$ =50V, $I_{D}$ =3.0A,		3.5			
Turn-Off Delay Time	$t_{d(off)}$	$R_{GEN}=2\Omega$		20.9		- ns	
Turn-Off Fall Time	t <sub>f</sub>			2.7			

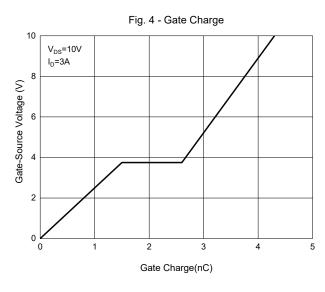


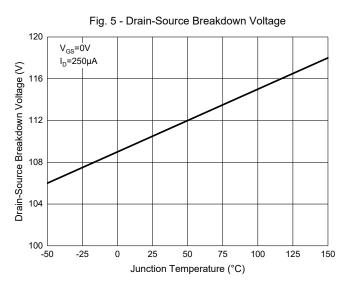
## **Curve Characteristics**

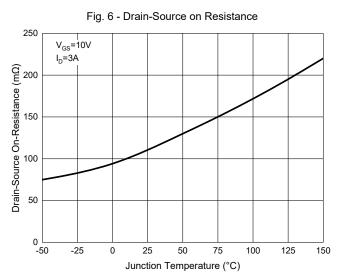






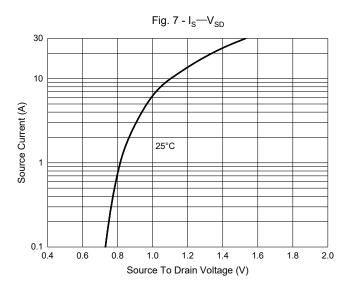


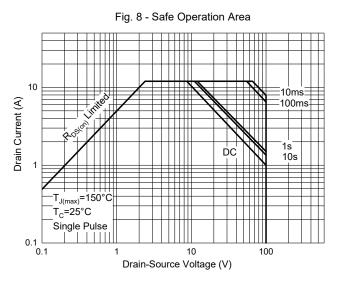


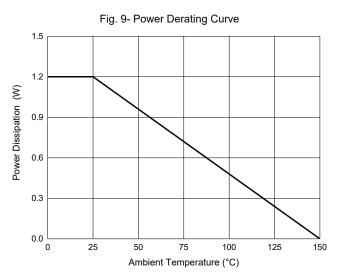




## **Curve Characteristics**



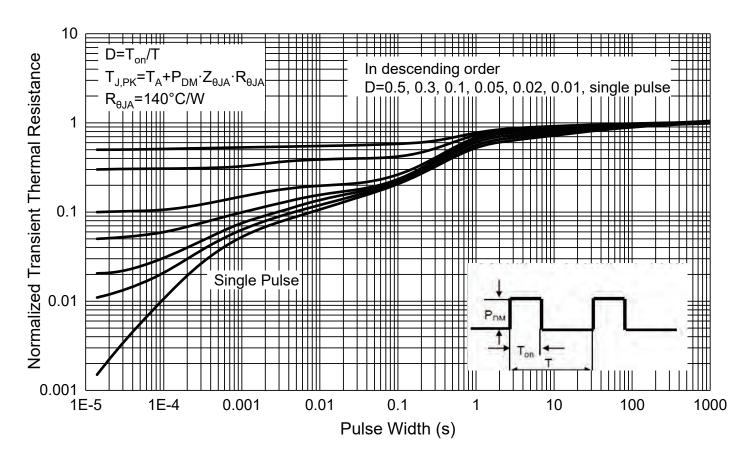






## **Curve Characteristics**

Fig. 10 - Normalized Maximum Transient Thermal Impedance





### **Ordering Information**

Device	Packing
Part Number-TP	Tape&Reel: 3Kpcs/Reel

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